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(54) Title: WAFER POLISHING SYSTEM AND WAFER TRANSFER METHOD

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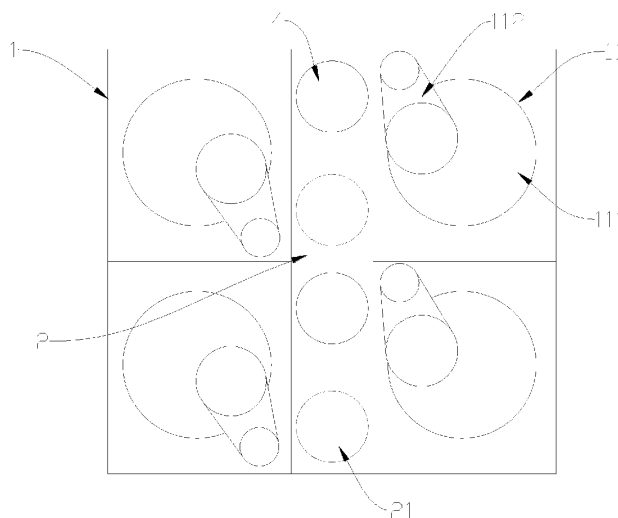


图 1-1

(57) Abstract: Disclosed in the present invention is a wafer polishing system, comprising polishing units. Each polishing unit comprises a wafer transfer channel and a polishing module; the polishing module comprises a polishing platform and a polishing arm, and the polishing arm can drive a wafer to move relative to the polishing platform; the wafer transfer channel is provided with at least two work stations, and a wafer loading/unloading table can move between the work stations; a transmission structure is provided between adjacent polishing units, a wafer is transferred between work stations of the adjacent polishing units along a first track, and the first track falls on wafer transfer channels; and/or a wafer loading/unloading table can move between adjacent polishing units; and/or a transfer structure is provided between a polishing unit and an external transition table, a wafer is transferred between work stations of the polishing unit

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and the external transition table along a second track, and the second track falls on a wafer transfer channel. Further disclosed in the present invention is a wafer transfer method. In the present invention, tracks all fall on wafer transfer channels, so that no other space is occupied, and the layout is reasonable; the process is flexible, and the processing efficiency is high; the transfer stability is high.

(57) 摘要: 本发明公开了一种晶圆抛光系统, 包括抛光单元; 抛光单元包括晶圆传输通道及抛光模组; 抛光模组包括抛光平台和抛光臂, 抛光臂可带动晶圆相对抛光平台活动; 晶圆传输通道上具有至少两个工作位, 晶圆装卸台可在工作位之间移动; 相邻抛光单元之间设有传递结构, 其沿着第一轨迹在两者的工作位之间传输晶圆, 第一轨迹落在晶圆传输通道上; 和/或, 晶圆装卸台可于相邻抛光单元之间移动; 和/或, 抛光单元和外界中转台之间设有传递结构, 其沿着第二轨迹在两者的工作位之间传输晶圆, 第二轨迹落在晶圆传输通道上。本发明还公开了一种晶圆传输方法。本发明轨迹都落在晶圆传输通道上, 不会占用别的空间, 布局合理; 工艺灵活, 加工效率高; 传输的稳定性高。